

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Canceled)

2. (Currently Amended) ~~The semiconductor device according to claim 1, A~~  
semiconductor device, comprising:  
a substrate including an electrode electrically connected to at least one  
integrated circuit;  
an external terminal electrically connected to the electrode;  
a light transmissive insulation layer disposed on the external terminal side of  
the substrate; and  
a mark provided on the substrate and covered by the light transmissive  
insulation layer so as to be visible through the insulation layer,  
wherein the substrate being-is a semiconductor substrate, and the integrated  
circuit being-is formed on the semiconductor substrate.

3. (Original) The semiconductor device according to claim 2, further comprising:  
a resin layer formed on the side of a semiconductor substrate where the  
electrode is formed, avoiding the location of the electrode; and  
an interconnection layer extending from the electrode to an upper surface of the  
resin layer and including at least one land formed on the resin layer;  
the external terminal being provided on the land; and  
the insulation layer being formed to cover the interconnection layer with at  
least a part of the external terminal exposed.

4. (Original) The semiconductor device according to claim 3, the mark being  
provided on the resin layer.

5. (Original) The semiconductor device according to claim 3, further comprising:

a passivation film provided on the semiconductor substrate,  
the mark being provided on the passivation film.

6. (Original) The semiconductor device according to claim 3, the mark being made of the same material as at least a part of the material which the interconnection layer is made of.

7. (Original) The semiconductor device according to claim 3, the mark being provided on an area not in contact with the interconnection layer.

8. (Original) The semiconductor device according to claim 3, the interconnection layer having a plurality of lands including a first land having a shape incorporating the mark and a second land having a shape different from the shape of the first land.

9. (Currently Amended) The semiconductor device according to ~~claim 1,~~ claim 2, the external terminal being a solder ~~ball;~~ ball, and the insulation layer being a solder resist.

10. (Currently Amended) The semiconductor device according to ~~claim 1,~~ claim 2, the semiconductor substrate being a semiconductor chip.

11. (Original) The semiconductor device according to claim 10, the mark being provided on at least one of the four corners of the semiconductor chip.

12. (Currently Amended) The semiconductor device according to ~~claim 1,~~ claim 2, the semiconductor substrate being a semiconductor wafer including the integrated circuit for each of plural areas.

13. (Currently Amended) A circuit ~~board comprising:~~ board, comprising a semiconductor device, the semiconductor device, comprising:

~~a semiconductor device according to claim 1 mounted thereon.~~

a substrate including an electrode electrically connected to at least one integrated circuit;

an external terminal electrically connected to the electrode;

a light transmissive insulation layer disposed on the external terminal side of the substrate; and

a mark provided on the substrate and covered by the light transmissive insulation layer so as to be visible through the insulation layer.

14. (Currently Amended) An electronic apparatus, comprising a circuit board according to claim 13.

~~\_\_\_\_\_ a semiconductor device according to claim 1.~~

15. (Currently Amended) A method of mounting a semiconductor device, comprising a substrate including an electrode electrically connected to at least one integrated circuit; an external terminal electrically connected to the electrode; a light transmissive insulation layer disposed on the external terminal side of the substrate; and a mark provided on the substrate and covered by the light transmissive insulation layer so as to be visible through the insulation layer, onto a ~~circuit-board according to claim 1, comprising:~~ board, the method comprising determining a mounting orientation of the semiconductor device by recognizing the mark ~~though~~ through the insulation layer.

16. (Currently Amended) A method of manufacturing ~~a semiconductor device, a circuit board,~~ comprising:

providing a mark on one side of a substrate having an electrode electrically connected to an integrated circuit;

providing an external terminal electrically connected to the electrode on the mark side of the substrate; and

providing a light transmissive insulation layer to cover the mark.